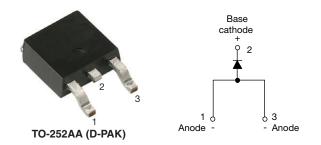
**Vishay Semiconductors** 

# High Voltage Surface Mount Input Rectifier Diode, 8 A



www.vishay.com

PRODUCT SUMMARY								
Package	TO-252AA (D-PAK)							
I <sub>F(AV)</sub>	8 A							
V <sub>R</sub>	1600 V							
V <sub>F</sub> at I <sub>F</sub>	1.1 V							
I <sub>FSM</sub>	150 A							
T <sub>J</sub> max.	150 °C							
Diode variation	Single die							

### **FEATURES**

- · Glass passivated pellet chip junction
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

### APPLICATIONS

- Input rectification
- Vishay Semiconductors switches and output rectifiers which are available in identical package outlines

### DESCRIPTION

The VS-8EWS16SPbF rectifier high voltage series has been optimized for very low forward voltage drop, with moderate leakage. The glass passivation technology used has reliable operation up to 150 °C junction temperature.

The high reverse voltage range available allows design of input stage primary rectification with outstanding voltage surge capability.

OUTPUT CURRENT IN TYPICAL APPLICATIONS									
APPLICATIONS	SINGLE-PHASE BRIDGE	THREE-PHASE BRIDGE	UNITS						
NEMA FR-4 or G10 glass fabric-based epoxy with 4 oz. (140 $\mu m)$ copper	1.2	1.6							
Aluminum IMS, R <sub>thCA</sub> = 15 °C/W	2.5	2.8	A						
Aluminum IMS with heatsink, $R_{thCA}$ = 5 °C/W	5.5	6.5							

#### Note

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•  $T_A = 55 \text{ °C}, T_J = 125 \text{ °C}, \text{ footprint } 300 \text{ mm}^2$ 

MAJOR RATINGS AND CHARACTERISTICS									
SYMBOL	CHARACTERISTICS	VALUES	UNITS						
I <sub>F(AV)</sub>	Sinusoidal waveform	8	A						
V <sub>RRM</sub>		1600	V						
I <sub>FSM</sub>		150	A						
V <sub>F</sub>	8 A, T <sub>J</sub> = 25 °C	1.10	V						
TJ		-40 to +150	°C						

VOLTAGE RATINGS										
PART NUMBER	V <sub>RRM</sub> , MAXIMUM PEAK REVERSE VOLTAGE V	V <sub>RSM</sub> , MAXIMUM NON-REPETITIVE PEAK REVERSE VOLTAGE V	I <sub>RRM</sub> AT 150 °C mA							
VS-8EWS16SPbF	1600	1700	0.5							



# **VS-8EWS16SPbF Series**



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ABSOLUTE MAXIMUM RATINGS									
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS					
Maximum average forward current	I <sub>F(AV)</sub>	$T_C = 105 \ ^{\circ}C$ , 180° conduction half sine wave	8						
Maximum peak one cycle	1	10 ms sine pulse, rated $V_{RRM}$ applied	125	А					
non-repetitive surge current	I <sub>FSM</sub>	10 ms sine pulse, no voltage reapplied							
Maximum I <sup>2</sup> t for fusing	l <sup>2</sup> t	10 ms sine pulse, rated V <sub>RRM</sub> applied	78	A <sup>2</sup> s					
Maximum 1-t for fusing	1-1	10 ms sine pulse, no voltage reapplied	A-S						
Maximum I <sup>2</sup> $\sqrt{t}$ for fusing	l²√t	t = 0.1 ms to 10 ms, no voltage reapplied	1100	A²√s					

ELECTRICAL SPECIFICATIONS									
PARAMETER	SYMBOL	TEST CO	NDITIONS	VALUES	UNITS				
Maximum forward voltage drop	V <sub>FM</sub>	8 A, T <sub>J</sub> = 25 °C		1.1	V				
Forward slope resistance	r <sub>t</sub>	T.I = 150 °C		20	mΩ				
Threshold voltage	V <sub>F(TO)</sub>	1j = 150 C		0.82	V				
Maximum reverse leakage current		T <sub>J</sub> = 25 °C V <sub>B</sub> = Rated V <sub>BBM</sub>		0.05	mA				
Maximum reverse leakage current	IRM	T <sub>J</sub> = 150 °C	VR - Haled VRRM	0.50	ША				

THERMAL - MECHANICAL SPECIFICATIONS								
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS				
Maximum junction and storage temperature range	T <sub>J</sub> , T <sub>Stg</sub>		-40 to +150	°C				
Maximum thermal resistance, junction to case	R <sub>thJC</sub>	DC operation	2.5	°C/W				
Typical thermal resistance, junction to ambient (PCB mount) <sup>(1)</sup>	R <sub>thJA</sub>		62	0/10				
Approximate weight			1	g				
Approximate weight			0.03	OZ.				
Marking device		Case style TO-252AA (D-PAK)	8EWS16S					

Note

<sup>(1)</sup> When mounted on 1" square (650 mm<sup>2</sup>) PCB of FR-4 or G-10 material 4 oz. (140 µm) copper 40 °C/W For recommended footprint and soldering techniques refer to application note #AN-994



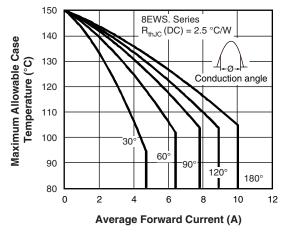


Fig. 1 - Current Rating Characteristics

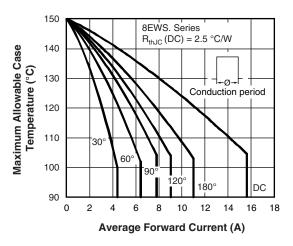


Fig. 2 - Current Rating Characteristics

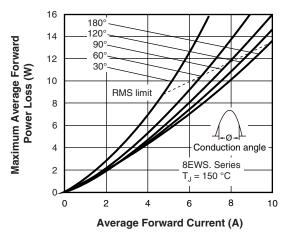
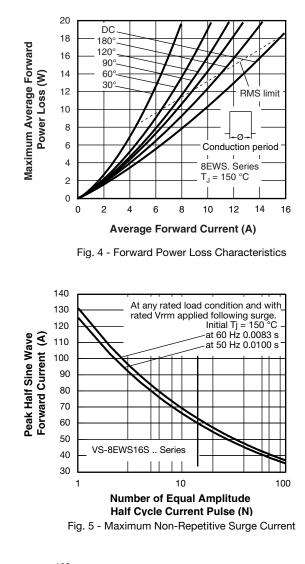


Fig. 3 - Forward Power Loss Characteristics

## **VS-8EWS16SPbF Series**

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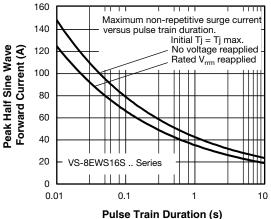


Fig. 6 - Maximum Non-Repetitive Surge Current

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# **VS-8EWS16SPbF Series**

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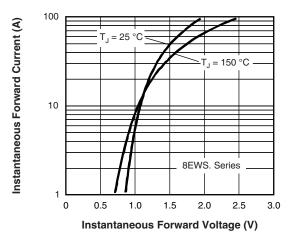


Fig. 7 - Forward Voltage Drop Characteristics

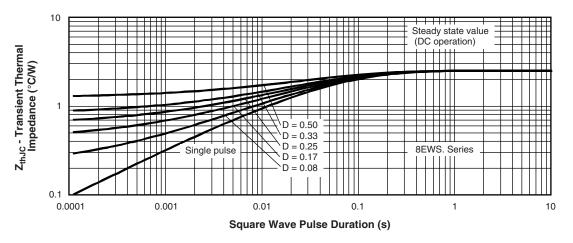


Fig. 8 - Thermal Impedance ZthJC Characteristics

## **Vishay Semiconductors**

**ORDERING INFORMATION TABLE** 

Device code	VS-	8	E	w	S	16	S	TR	PbF		
	1	2	3	4	5	6	7	8	9		
	<ol> <li>Vishay Semiconductors product</li> <li>Current rating (8 = 8 A)</li> <li>Circuit configuration: E = single diode</li> </ol>										
	4 -	Pac	kage: D-PAK								
	5 -	Тур	e of silic	on:							
				d recove	-						
	6 -		-	ng (16 =		)					
	- [7]	- S = surface mountable									
	8 -	- • TR = tape and reel									
		<ul> <li>TRR = tape and reel (right oriented)</li> </ul>									
		• TF	RL = tap	e and re	el (left d	priented	)				
	9 -	PbF	= lead	(Pb)-fre	е						

LINKS TO RELATED DOCUMENTS								
Dimensions	www.vishay.com/doc?95016							
Part marking information	www.vishay.com/doc?95059							
Packaging information	www.vishay.com/doc?95033							

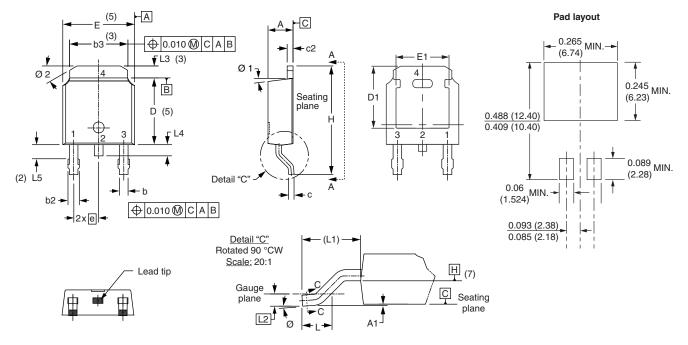






D-PAK (TO-252AA)

### **DIMENSIONS** in millimeters and inches



SYMBOL	MILLIM	IETERS	INC	HES	NOTES	SYMBOL	MILLIN	IETERS	INC	HES	NOTES	
STNIBOL	MIN.	MAX.	MIN.	MAX.	NOTES		STIVIDUL	MIN.	MAX.	MIN.	MAX.	NOTES
А	2.18	2.39	0.086	0.094			е	2.29	BSC	0.090	BSC	
A1	-	0.13	-	0.005			Н	9.40	10.41	0.370	0.410	
b	0.64	0.89	0.025	0.035			L	1.40	1.78	0.055	0.070	
b2	0.76	1.14	0.030	0.045			L1	2.74	BSC	0.108	REF.	
b3	4.95	5.46	0.195	0.215	3		L2	0.51 BSC		0.020 BSC		
с	0.46	0.61	0.018	0.024			L3	0.89	1.27	0.035	0.050	3
c2	0.46	0.89	0.018	0.035			L4	-	1.02	-	0.040	
D	5.97	6.22	0.235	0.245	5		L5	1.14	1.52	0.045	0.060	2
D1	5.21	-	0.205	-	3		Ø	0°	10°	0°	10°	
E	6.35	6.73	0.250	0.265	5		Ø1	0°	15°	0°	15°	
E1	4.32	-	0.170	-	3		Ø2	25°	35°	25°	35°	

#### Notes

<sup>(1)</sup> Dimensioning and tolerancing as per ASME Y14.5M-1994

(2) Lead dimension uncontrolled in L5

<sup>(3)</sup> Dimension D1, E1, L3 and b3 establish a minimum mounting surface for thermal pad

(4) Section C - C dimension apply to the flat section of the lead between 0.13 and 0.25 mm (0.005 and 0.10") from the lead tip

(5) Dimension D, and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body

<sup>(6)</sup> Dimension b1 and c1 applied to base metal only

<sup>(7)</sup> Datum A and B to be determined at datum plane H

<sup>(8)</sup> Outline conforms to JEDEC outline TO-252AA

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